

CLAIMS:

1. A probe card for testing electronic elements comprising:

(a) a substrate having electrical circuitry thereon;

(b) an encapsulant layer overlying said substrate; and

(c) a plurality of flexible leads extending through said encapsulant layer, said leads having terminals projecting above said encapsulant layer and exposed for engagement with contact pads on a electronic element.

2. A probe card as claimed in claim 1 wherein said terminals have sharp features.

3. A probe card as claimed in claim 2 wherein said terminals have points.

4. A probe card as claimed in claim 1 wherein said encapsulant layer has channels therein subdividing the encapsulant layer into a plurality of portions, said portions of said encapsulant layer being deformable independently of one another.

5. A probe card as claimed in claim 1 wherein said terminals are physically connected to one another solely by said encapsulant layer and said leads.

6. A probe card as claimed in claim 1 further comprising a flexible dielectric layer overlying said encapsulant layer, said flexible dielectric layer having a top surface facing away from said encapsulant layer and substrate, said terminals being attached to said flexible dielectric layer and exposed at the top surface of said flexible dielectric layer.

7. A probe card as claimed in claim 1 wherein at least some of said leads are multiconductor leads, each such multiconductor lead including a plurality of lead conductors

and a dielectric material disposed between said lead conductors, said terminals including sets of plural closely-spaced terminals, at least some of said multiconductor leads being connected to said closely-spaced terminal sets so that the conductors on each such multiconductor lead are connected to terminals of the same set.